L Number	Hits	Search Text	DB	Time stamp
4	11212		USPAT;	2004/11/03 21:36
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
5	·22	(MES or "manufacturing execution system")	USPAT;	2004/11/03 20:17
		same (in-line or inline or "in line")	US-PGPUB;	, , ,
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
6	1	"6173750".PN.	USPAT	2004/11/03 20:20
169	55	(US-6337221-\$ or US-6553276-\$ or	USPAT;	2004/11/03 20:56
		US-6363295-\$ or US-5907492-\$ or US-5915231-\$	US-PGPUB	
		or US-4915565-\$ or US-4759675-\$ or		
		US-4685998-\$ or US-4627787-\$ or US-4627151-\$		
		or US-6124637-\$ or US-5985695-\$ or		
		US-5859475-\$ or US-5844803-\$ or US-6256549-\$	İ	
		or US-6677219-\$ or US-6551860-\$ or		
		US-6521468-\$ or US-6507096-\$ or US-6372526-\$		
		or US-6217949-\$ or US-6174752-\$ or		
		US-6045652-\$ or US-5985377-\$ or US-5750421-\$		
1		or US-5565008-\$).did. or (US-4683644-\$ or		
1		US-6284566-\$ or US-6549821-\$ or US-6392286-\$		
		or US-6589801-\$ or US-6537848-\$ or		
		US-6432752-\$ or US-6417028-\$ or US-6015722-\$		
		or US-5336931-\$ or US-6230719-\$ or		
		US-6656768-\$ or US-6162661-\$ or US-5946553-\$		
		or US-5834336-\$ or US-5817545-\$ or		
		US-5620927-\$ or US-6333210-\$ or US-6602430-\$		
		or US-6730545-\$ or US-6730532-\$).did. or		
		(US-20010051394-\$ or US-20020082740-\$ or		
		US-20030191550-\$ or US-20030003622-\$ or		
į l		US-20010037568-\$ or US-20030093173-\$ or		
i		US-20030020509-\$ or US-20020181758-\$).did.		
172	2	((US-6337221-\$ or US-6553276-\$ or	USPAT;	2004/11/03 20:56
	_	US-6363295-\$ or US-5907492-\$ or US-5915231-\$	US-PGPUB;	2001, 11, 03 20.30
i		or US-4915565-\$ or US-4759675-\$ or	EPO; JPO;	
		US-4685998-\$ or US-4627787-\$ or US-4627151-\$	DERWENT;	
		or US-6124637-\$ or US-5985695-\$ or	IBM TDB	
		US-5859475-\$ or US-5844803-\$ or US-6256549-\$	12122	
		or US-6677219-\$ or US-6551860-\$ or		
		US-6521468-\$ or US-6507096-\$ or US-6372526-\$		
		or US-6217949-\$ or US-6174752-\$ or		
1		US-6045652-\$ or US-5985377-\$ or US-5750421-\$		
		or US-5565008-\$).did. or (US-4683644-\$ or		
		US-6284566-\$ or US-6549821-\$ or US-6392286-\$		
		or US-6589801-\$ or US-6537848-\$ or		
		US-6432752-\$ or US-6417028-\$ or US-6015722-\$		
		or US-5336931-\$ or US-6230719-\$ or		
		US-6656768-\$ or US-6162661-\$ or US-5946553-\$		
1		or US-5834336-\$ or US-5817545-\$ or		
		US-5620927-\$ or US-6333210-\$ or US-6602430-\$		
		or US-6730545-\$ or US-6730532-\$).did. or		
		(US-20010051394-\$ or US-20020082740-\$ or	i	
		US-20030191550-\$ or US-20030003622-\$ or		
		US-20010037568-\$ or US-20030093173-\$ or		
		US-20030020509-\$ or US-20020181758-\$).did.)		·
		and (MES or "manufacturing execution		
		system")		
		L	L	L

		reserved to the contract of th		1 1 1	\neg
173	4	((US-6337221-\$ or US-6553276-\$ or	USPAT;	2004/11/03 21:28	.
	•	US-6363295-\$ or US-5907492-\$ or US-5915231-\$	US-PGPUB;		-
		or US-4915565-\$ or US-4759675-\$ or	EPO; JPO;		-
		US-4685998-\$ or US-4627787-\$ or US-4627151-\$	DERWENT;		
		or US-6124637-\$ or US-5985695-\$ or	IBM_TDB		
		US-5859475-\$ or US-5844803-\$ or US-6256549-\$	_		-
	i	or US-6677219-\$ or US-6551860-\$ or			1
		US-6521468-\$ or US-6507096-\$ or US-6372526-\$	ł		1
		or US-6217949-\$ or US-6174752-\$ or			1
		US-6045652-\$ or US-5985377-\$ or US-5750421-\$			1
	İ	or US-5565008-\$).did. or (US-4683644-\$ or			-
		US-6284566-\$ or US-6549821-\$ or US-6392286-\$			1
		or US-6589801-\$ or US-6537848-\$ or		i	1
		US-6432752-\$ or US-6417028-\$ or US-6015722-\$			İ
		or US-5336931-\$ or US-6230719-\$ or			
		,			Ì
		US-6656768-\$ or US-6162661-\$ or US-5946553-\$			
	ļ	or US-5834336-\$ or US-5817545-\$ or			-
		US-5620927-\$ or US-6333210-\$ or US-6602430-\$			
,		or US-6730545-\$ or US-6730532-\$).did. or	1		
1		(US-20010051394-\$ or US-20020082740-\$ or			1
l l		US-20030191550-\$ or US-20030003622-\$ or			
l l		US-20010037568-\$ or US-20030093173-\$ or		· ·	-
		US-20030020509-\$ or US-20020181758-\$).did.)	ļ		1
		and (manag\$8)			ł
174	544	(MES or "manufacturing execution system")	USPAT;	2004/11/03 20:58	
		same (semiconductor or wafer)	US-PGPUB;		
			EPO; JPO;		
			DERWENT;	· ·	
		'	IBM TDB		
175	1117	(MES or "manufacturing execution system")	USPAT;	2004/11/03 22:02	
1		and (semiconductor or wafer)	US-PGPUB;		
1			EPO; JPO;		
·			DERWENT;		
1			IBM TDB		
176	602	(MES or "manufacturing execution system")	USPAT;	2004/11/03 20:58	
	1	and (semiconductor or wafer) and line	US-PGPUB;		
		The transfer of water, and time	EPO; JPO;		
			DERWENT;		1
			IBM TDB		
177	270	((MES or "manufacturing execution system")	USPAT;	2004/11/03 20:59	
111	2,0	same (semiconductor or wafer)) and line	US-PGPUB;	2004/11/03 20:59	
		same (semiconductor or water)) and line			
 -			EPO; JPO;		
ļ		,	DERWENT;		
170	_	//MDC on Boom Franchista and the control of the con	IBM_TDB	0004/11/05 55 ==	
178	3		USPAT;	2004/11/03 20:59	
		same (semiconductor or wafer)) and line and	US-PGPUB;		
		(camera or vision\$6)	EPO; JPO;		
			DERWENT;		
			IBM_TDB		-
181	2452	700/95,117,121,96.ccls.	USPAT;	2004/11/03 21:31	
	, .		US-PGPUB;	[
Ì			EPO; JPO;		
			DERWENT;		
			IBM TDB		

				1 1 1
182	2	((US-6337221-\$ or US-6553276-\$ or US-6363295-\$ or US-5907492-\$ or US-5915231-\$ or US-4915565-\$ or US-4759675-\$ or US-4685998-\$ or US-4627787-\$ or US-4627151-\$ or US-6124637-\$ or US-5985695-\$ or US-5859475-\$ or US-5844803-\$ or US-6256549-\$ or US-6677219-\$ or US-6551860-\$ or US-6521468-\$ or US-6551860-\$ or US-6521468-\$ or US-657096-\$ or US-6372526-\$ or US-6217949-\$ or US-6174752-\$ or US-6045652-\$ or US-5985377-\$ or US-5750421-\$ or US-5565008-\$).did. or (US-4683644-\$ or US-6284566-\$ or US-6549821-\$ or US-6392286-\$ or US-6589801-\$ or US-6537848-\$ or US-6589801-\$ or US-6537848-\$ or US-653931-\$ or US-66015722-\$ or US-656768-\$ or US-6162661-\$ or US-5946553-\$ or US-5834336-\$ or US-6162661-\$ or US-5946553-\$ or US-5834336-\$ or US-6162661-\$ or US-6602430-\$ or US-6730545-\$ or US-6730532-\$).did. or (US-20010051394-\$ or US-20020082740-\$ or US-20030191550-\$ or US-20030093173-\$ or US-20030020509-\$ or US-20020181758-\$).did.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 21:37
183	1122	and (host\$8) 700/95,117,121,96;438/106,107,110-113,118,127 and @pd>=20040202	CUSTRAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/11/03 21:32
184	929	700/95,117,121,96;438/106,107,110-113,118,127 and @pd>=20040202 and (semiconductor or wafer)	distrat; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/11/03 21:32
185	576	700/95,117,121,96;438/106,107,110-113,118,127 and @pd>=20040202 and (semiconductor or wafer) and line	CMSTRAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/11/03 21:32
186	36	(MES or "manufacturing execution system") same (reject\$5 or "quality control")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/11/03 21:55
187	24	((US-6337221-\$ or US-6553276-\$ or US-6363295-\$ or US-5907492-\$ or US-5915231-\$ or US-4915565-\$ or US-4759675-\$ or US-4685998-\$ or US-4627787-\$ or US-4627151-\$ or US-6124637-\$ or US-5985695-\$ or US-5859475-\$ or US-5859475-\$ or US-6551860-\$ or US-6677219-\$ or US-6551860-\$ or US-6521468-\$ or US-6507096-\$ or US-6372526-\$ or US-6217949-\$ or US-6174752-\$ or US-6217949-\$ or US-6174752-\$ or US-5864562-\$ or US-5985377-\$ or US-5750421-\$ or US-565008-\$).did. or (US-4683644-\$ or US-6284566-\$ or US-6549821-\$ or US-6392286-\$ or US-6589801-\$ or US-6537848-\$ or US-6432752-\$ or US-6417028-\$ or US-6015722-\$ or US-653666768-\$ or US-6230719-\$ or US-6656768-\$ or US-6162661-\$ or US-5946553-\$ or US-5834336-\$ or US-5817545-\$ or US-5620927-\$ or US-6333210-\$ or US-6602430-\$ or US-5730545-\$ or US-6333210-\$ or US-6602430-\$ or US-200300191550-\$ or US-20030003622-\$ or US-20030027568-\$ or US-20030093173-\$ or US-20030020509-\$ or US-20030093173-\$ or US-20030020509-\$ or US-20020181758-\$).did.) and (central\$8)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 21:37

196	38	(MES or "manufacturing execution system") same (categor\$9)	USPAT; US-PGPUB; EPO; JPO;	2004/11/03 21:55
			DERWENT; IBM_TDB	
205	52	(MES or "manufacturing execution system") and (semiconductor or wafer) and (in-line or inline or "in line")	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/11/03 22:03
206	57	(MES or "manufacturing execution system") and (semiconductor or wafer) and (in-line or inline or "in line" or "assembly line")	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/11/03 22:40
230	8	CHANG-BO-SOON CHANG-BO-S	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/11/03 23:14
-	10	CHANG-BO-SOON CHANG-BO-S CHANG-BO-H CHANG-BO-E	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/02/01 15:50
-	869	700/121.ccls.	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/01/29 18:22
-	25	700/121.ccls. and ("back-end" or "back end")	DERWENT; IBM_TDB USPAT; US-PGPUB;	2004/01/29 16:18
-	2457	(die or chip or IC or wafer) and (cure or curing or cured) and bond\$9 and (plasma or	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	2004/01/29 18:59
		clean\$6) and (encapsulat\$6 or mold\$8) and (dicing or diced or dice or saw\$6 or singulat\$8 or cut\$8) and (camera or vision or test\$6) and (convey\$6 or transport\$6)	EPO; JPO; DERWENT; IBM_TDB	
_	0	700/121.ccls. and (die or chip or IC or wafer) and (cure or curing or cured) and bond\$9 and (plasma or clean\$6) and (encapsulat\$6 or mold\$8) and (dicing or diced or dice or saw\$6 or singulat\$8 or	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/30 12:48
-	24	cut\$8) and (camera or vision or test\$6) and (convey\$6 or transport\$6) ((die or chip or IC or wafer) and (cure or curing or cured) and bond\$9 and (plasma or clean\$6) and (encapsulat\$6 or mold\$8) and (dicing or diced or dice or saw\$6 or	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/01/29 18:32
-	55	singulat\$8 or cut\$8) and (camera or vision or test\$6) and (convey\$6 or transport\$6)) and line and ("back end" or "back-end") ((die or chip or IC or wafer) and (cure or curing or cured) and bond\$9 and (plasma or	IBM_TDB USPAT; US-PGPUB;	2004/01/29 19:00
		clean\$6) and (encapsulat\$6 or mold\$8) and (dicing or diced or dice or saw\$6 or singulat\$8 or cut\$8) and (camera or vision or test\$6) and (convey\$6 or transport\$6))	EPO; JPO; DERWENT; IBM_TDB	
-	0	and ("assembly line") 700/121.ccls. and (die or chip or IC or wafer) and (cure or curing or cured) and bond\$9 and (plasma or clean\$6) and (encapsulat\$6 or mold\$8) and (dicing or	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/01/30 12:50
		diced or dice or saw\$6 or singulat\$8 or cut\$8) and (convey\$6 or transport\$6)	IBM_TDB	

-	0	700/121.ccls. and bond\$9 and (cure or cured or curing) and (plasma or clean\$6) and	USPAT; US-PGPUB;	2004/01/30 13:00
		(encapsulat\$6 or mold\$8) and (convey\$6 or	EPO; JPO;	·
		transport\$6)	DERWENT;	
_	2	700/121.ccls. and bond\$9 and (plasma or	IBM_TDB USPAT;	2004/01/30 13:05
	-	clean\$6) and (encapsulat\$6 or mold\$8) and	US-PGPUB;	2001,01,30 13.05
		(convey\$6 or transport\$6)	EPO; JPO;	
			DERWENT; IBM TDB	
_	687	"strip die" or "strip-die"	USPAT;	2004/01/30 13:06
	1		US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM_TDB	
-	185	700/96.ccls.	USPAT;	2004/01/30 14:00
	:		US-PGPUB; EPO; JPO;	
	:		DERWENT;	
	0000	420/106 107 7717	IBM_TDB	2004/01/21 16 25
_	8282	438/106-127.ccls.	USPAT; US-PGPUB;	2004/01/31 16:35
			EPO; JPO;	
			DERWENT;	
_	163	438/106-127.ccls. and (conveyor or	IBM_TDB USPAT;	2004/01/30 18:19
		conveyance or transporter)	US-PGPUB;	, , ==:=•
			EPO; JPO; DERWENT;	
			IBM_TDB	
-	100	700/230.ccls.	USPAT;	2004/01/30 15:25
			US-PGPUB; EPO; JPO;	
			DERWENT;	
	7	/#2600076#	IBM_TDB	2004/01/20 10 00
_	/	("3698076" "4139726" "5173766" "5594234" "5844803" "5909053"	USPAT	2004/01/30 18:02
•		"5943558" "2001/0041424" "2002/0020929"		
_	0	"2002/0031867" "2002/0037604").PN. 6521468.URPN.	USPAT	2004/01/30 18:10
-	16	("2869053" "3577633" "3689991"	USPAT	2004/01/30 18:10
		"3838984" "4411719" "4466183"		
		"4806409" "4811081" "4944850" "4949155" "4961984" "5063434"		
]	"5133118" "5148266" "5442229"		
_	16	"5541451").PN. 438/106-127.ccls. and (attach\$5) and (cure	USPAT:	2004/02/03 11:22
		or cured or curing) and bond and (mold\$6 or	US-PGPUB;	2001, 02, 03 111.22
		encapsulat\$6) and (saw\$6 or singulat\$6) and test\$6 and sort\$6	EPO; JPO;	
		reacho and antibo	DERWENT; IBM TDB	
-	71	(attach\$5) and (cure or cured or curing) and	USPAT;	2004/01/30 19:29
		bond and (mold\$6 or encapsulat\$6) and (saw\$6 or singulat\$6) and test\$6 and sort\$6 and	US-PGPUB; EPO; JPO;	
		(conveyor or conveyance or transporter or	DERWENT;	
		conveyed)	IBM_TDB	2004/01/20 10 15
_	52	438/106.ccls. and (conveyor or conveyance or conveyed or transporter)	USPAT; US-PGPUB;	2004/01/30 19:42
		· ·	EPO; JPO;	
			DERWENT; IBM TDB	
_	63	(wire near bond\$6) and (die near attach\$8)	USPAT;	2004/01/30 19:43
		and singulat\$6 and (conveyor or conveyance	US-PGPUB;	
		or conveyed or transporter)	EPO; JPO; DERWENT;	
		(11471404711 117747111 117747111111111111111	IBM_TDB	
-	14	("4740247" "5564159" "5663593" "5677569" "5706178" "5708567"	USPAT	2004/01/30 20:06
		"5712570" "5729050" "5741729"		
		"5748450" "5783220" "5796170" "5821613" "6072233").PN.		
	0	6392286.URPN.	USPAT	2004/01/30 20:09

-	418	438/112.ccls.	USPAT; US-PGPUB;	2004/01/31 15:56
			EPO; JPO; DERWENT; IBM TDB	
-	339	438/106-127.ccls. and ("in-line" or "in line")	USPAT; US-PGPUB;	2004/01/31 17:27
			EPO; JPO; DERWENT; IBM TDB	
-	39	438/106-127.ccls. and ("in-line" or "in line") and (plasma)	USPAT; US-PGPUB;	2004/01/31 17:18
			EPO; JPO; DERWENT; IBM TDB	
-	26	438/106-127.ccls. and ((plasma with clean\$6) same (attach or bond))	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/01/31 17:20
-	119	ST-ASSEMBLY-TEST-SERVICES-LIMI	IBM_TDB USPAT; US-PGPUB;	2004/01/31 17:20
		ST-ASSEMBLY-TEST-SERVICES-LTD ST-ASSEMBLY-TEST-SERVICES-PTE-LTD ST-ASSEMBLY-TEST-SERVICE-LTD ST-ASSEMBY-TEST-SERVICES-PTE-LTD	EPO; JPO; DERWENT; IBM_TDB	
-	49	(ST-ASSEMBLY-TEST-SERVICES ST-ASSEMBLY-TEST-SERVICES-LIMI ST-ASSEMBLY-TEST-SERVICES-LTD ST-ASSEMBLY-TEST-SERVICES-PTE-LTD	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/01/31 17:21
		ST-ASSEMBLY-TEST-SERVICE-LTD ST-ASSEMBY-TEST-SERVICES-PTE-LTD) and (conveyor or conveyance or conveyed or transport\$9 or transfer\$9)	IBM_TDB	
-	2	6230719.pn.	USPAT; US-PGPUB; EPO; JPO;	2004/01/31 17:24
-	11	438/106-127.ccls. and (conveyor).ab.	DERWENT; IBM_TDB USPAT; US-PGPUB;	2004/01/31 17:29
			EPO; JPO; DERWENT; IBM_TDB	
-	161	438/106-127.ccls. and (conveyor or conveyance)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/02/02 14:50
_	4	438/106-127.ccls. and (conveyor or conveyance) same (plasma)	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/01/31 18:22
-	811	438/106-127.ccls. and integration	DERWENT; IBM_TDB USPAT; US-PGPUB;	2004/01/31 18:22
	77	438/106-127.ccls. and (integration same	EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/01/31 18:22
		line)	US-PGPUB; EPO; JPO; DERWENT;	
-	4	SONG-KONG-LAM	IBM_TDB USPAT; US-PGPUB;	2004/02/01 15:53
			EPO; JPO; DERWENT; IBM_TDB	

	·			
-	721	INTEGRATED-DEVICE-TECHNOLOGY	USPAT;	2004/02/01 15:54
		INTEGRATED-DEVICE-TECHNOLOGY-INC	US-PGPUB;	
		INTEGRATED-DEVICE-TECH	EPO; JPO;	
		INTEGRATED-DEVICE-TECHNOLOGIES-INC	DERWENT;	İ
		INTEGRATED-DEVICE-TECHNOL-INC	IBM_TDB	
		INTEGRATED-DEV-TECH		
-	5	(INTEGRATED-DEVICE-TECHNOLOGY	USPAT;	2004/02/01 15:56
		INTEGRATED-DEVICE-TECHNOLOGY-INC	US-PGPUB;	
		INTEGRATED-DEVICE-TECH	EPO; JPO;	!
		INTEGRATED-DEVICE-TECHNOLOGIES-INC	DERWENT;	
		INTEGRATED-DEVICE-TECHNOL-INC	IBM TDB	
		INTEGRATED-DEV-TECH) and (conveyor or	_	
ļ		offloader or onloader or transporter or		·
		loader)		
_	5	CHOE-PENG-CHEONG CHOE-P-C	USPAT;	2004/02/01 15:56
			US-PGPUB;	
Ì			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	401	438/106-127.ccls. and (camera or vision\$6)	USPAT;	2004/02/02 14:51
		155, 255 11, 15515, 1114 (54, 115, 115, 115, 115, 115, 115, 115, 1	US-PGPUB;	
}			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	31	438/106-127.ccls. and ((camera or vision\$6)	USPAT;	2004/02/02 16:42
		with automat\$9)	US-PGPUB;	2001, 02, 02 10.42
		The decomacy of	EPO; JPO;	
			DERWENT;	
			IBM TDB	ļ
_	۸ ا	438/106-127.ccls. and ((camera or vision\$6)	USPAT;	2004/02/02 16:45
_	*	with tape with reel)	US-PGPUB;	2004/02/02 10:45
		with tape with reel/	EPO; JPO;	1
			DERWENT;	
			IBM TDB	
	41	438/106-127.ccls. and (camera or	USPAT;	2004/02/02 17:02
_	#1	vision\$6).ab.	US-PGPUB;	2004/02/02 17:02
		VISIONSO, ab.	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	_ E0	438/106-127.ccls. and ((camera or vision\$6)	USPAT;	2004/02/03 11:44
-	39	with (packag\$6))	US-PGPUB;	2004/02/03 11:44
	i	with (packagse))	EPO; JPO;	
			DERWENT;	
			IBM TDB	
	_	438/106-127.ccls. and ((machine or	USPAT;	2004/02/03 11:25
-	,		· ·	2004/02/03 11:25
		equipment) near integration)	US-PGPUB; EPO; JPO;	
	1	·	DERWENT;	
	i		IBM TDB	
_	10	438/106-127.ccls. and ((machine or	USPAT;	2004/02/03 11:25
	"	equipment) with integration)	US-PGPUB;	2004,02,03 11.23
-	1	equipment, with integration,	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	27	RODGERS-THURMAN-J RODGERS-THURMAN-JOHN	USPAT;	2004/02/03 11:42
		VERMA-V VERMA-VANI	US-PGPUB;	2004,02,03 11:42
	1	ADIGID A ADIGID-ADIAT	EPO; JPO;	
	1		DERWENT;	
	1		IBM TDB	
_	,	438/106-127.ccls. and ((camera or vision\$6)	USPAT;	2004/02/03 12:24
		with (sort\$6))	US-PGPUB;	2007/02/03 12:24
	[WICH (BOICHO!)	EPO; JPO;	
			DERWENT;	
	[IBM TDB	
-	17	438/106-127.ccls. and ((camera or vision\$6)	USPAT;	2004/02/03 12:42
	'	with (inspect\$6))	US-PGPUB;	2004/02/03 12:42
		(Impeded)//	EPO; JPO;	
			DERWENT;	
]		IBM TDB	
	L	L	TDM_TDB	

-	488	438/106-127;700/121.ccls. and	(camera or	USPAT;	2004/02/03 1	2:42
		vision\$6)		US-PGPUB;		1
				EPO; JPO;		
				DERWENT;		
				IBM TDB		
_	42	438/106-127;700/121.ccls. and	((camera or	USPAT;	2004/02/03 1	2:42
		vision\$6) with line)		US-PGPUB;		
				EPO; JPO;		
		•		DERWENT;		
				IBM TDB		